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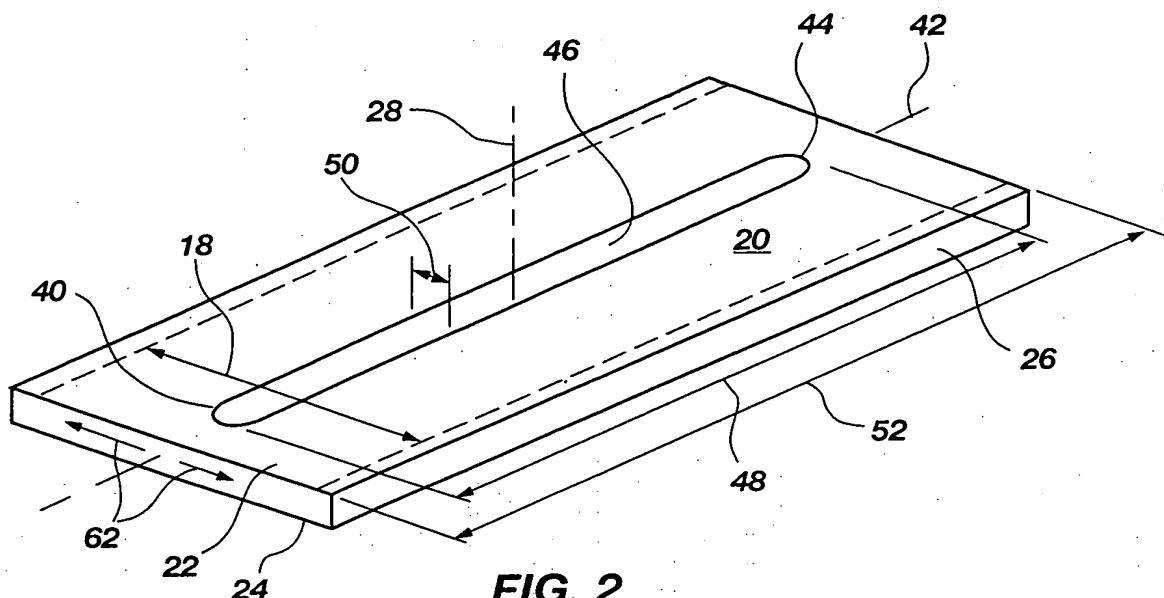


FIG. 2
(PRIOR ART)

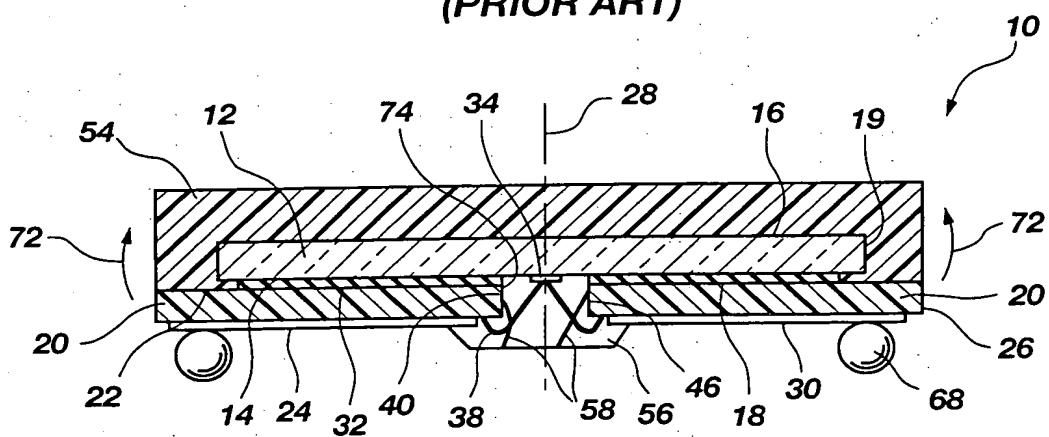


FIG. 1
(PRIOR ART)

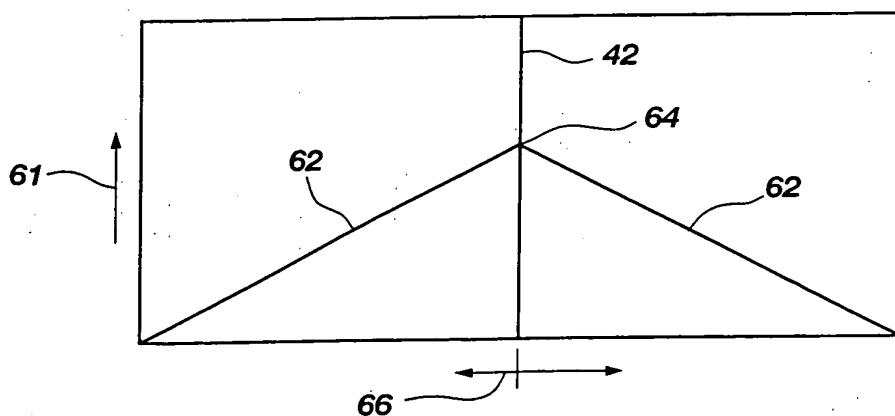


FIG. 3

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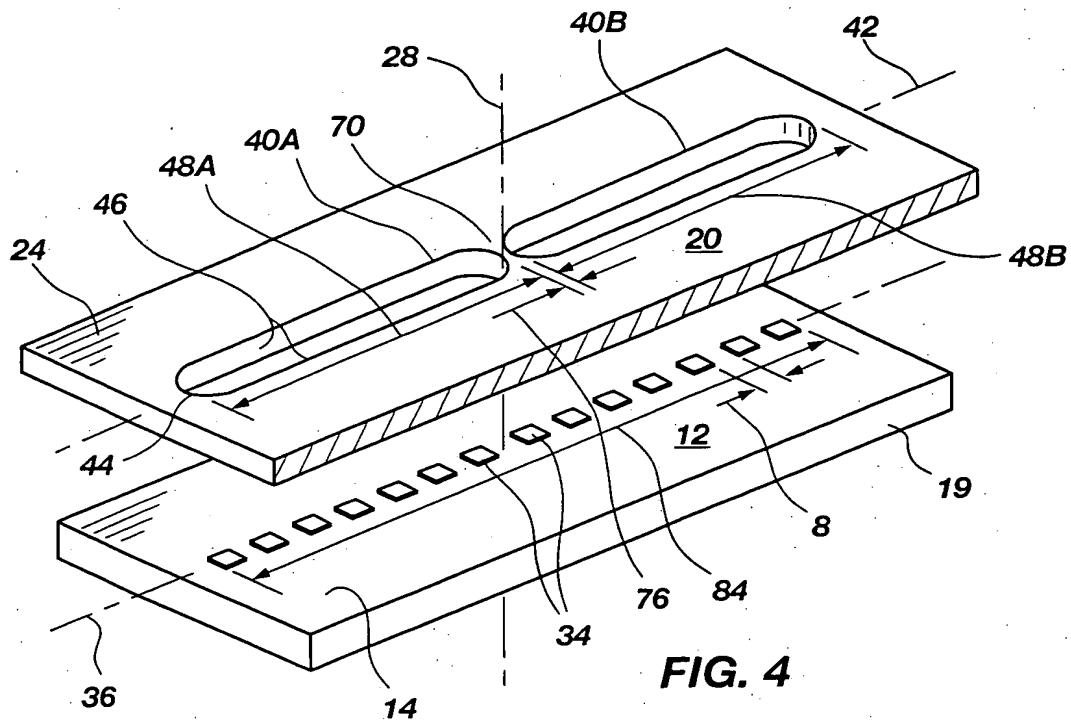


FIG. 4

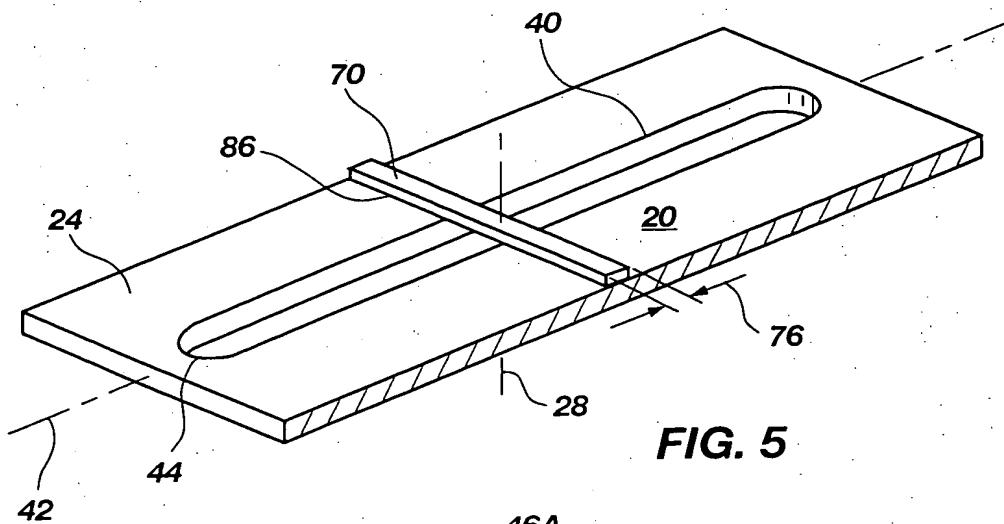


FIG. 5

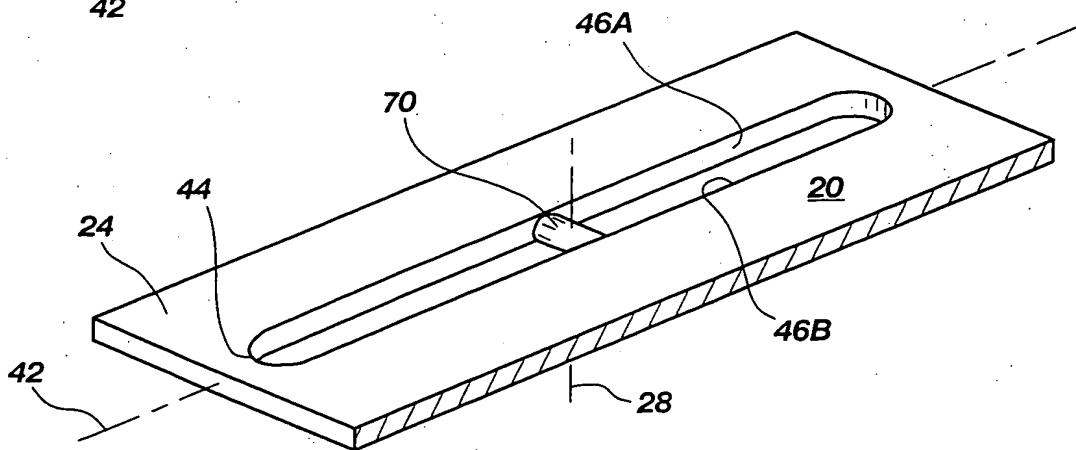


FIG. 6

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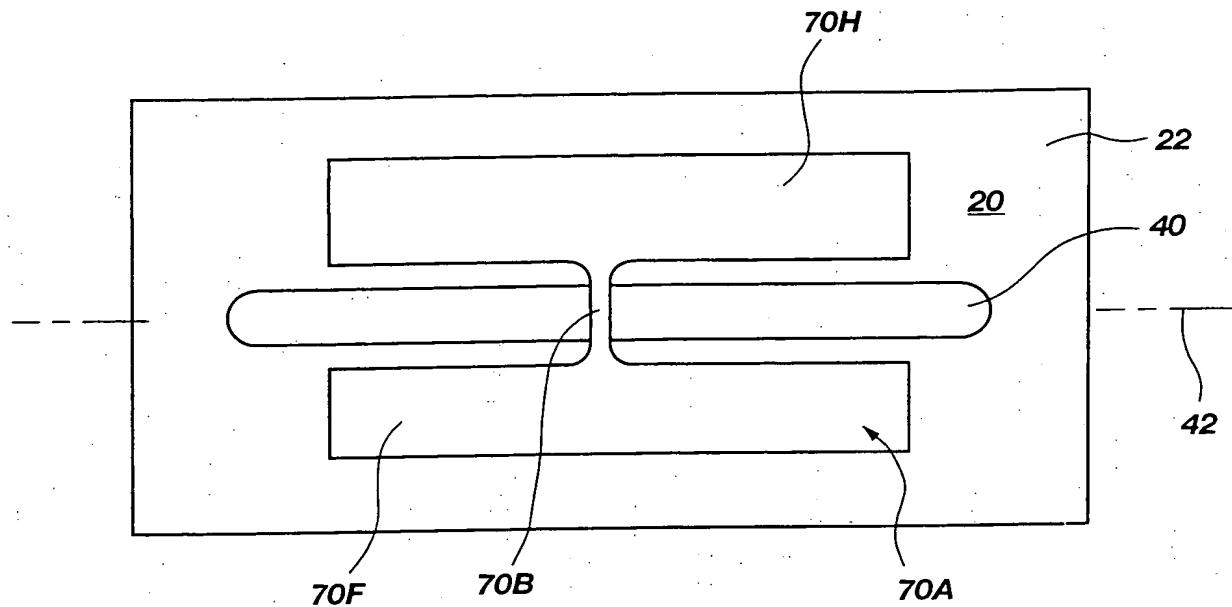


FIG. 5A

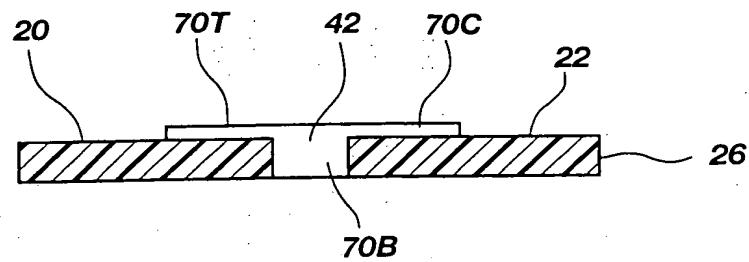


FIG. 7

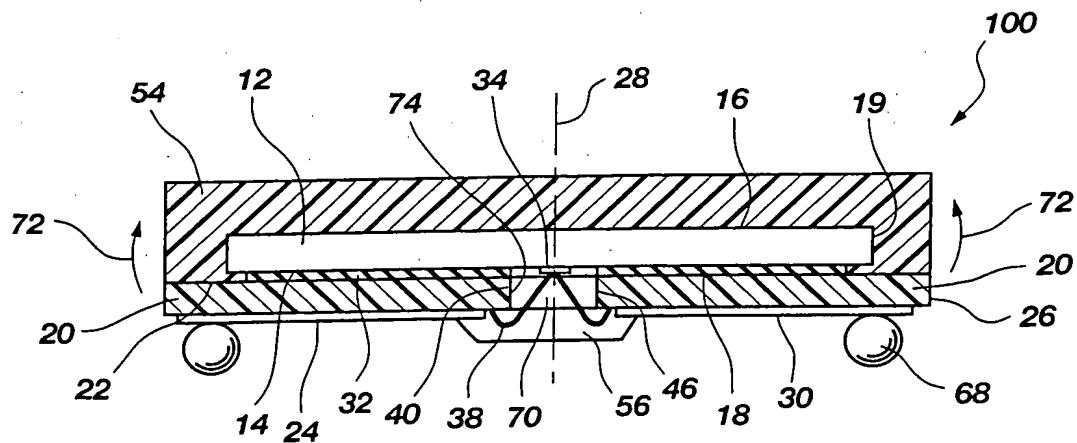


FIG. 8

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TITLE: SEMICONDUCTOR DIE CONFIGURED FOR USE WITH
INTERPOSER SUBSTRATES HAVING REINFORCED
INTERCONNECT SLOTS

Inventor: Blaine J. Thurgood

Docket No.: 2269-5520.2US

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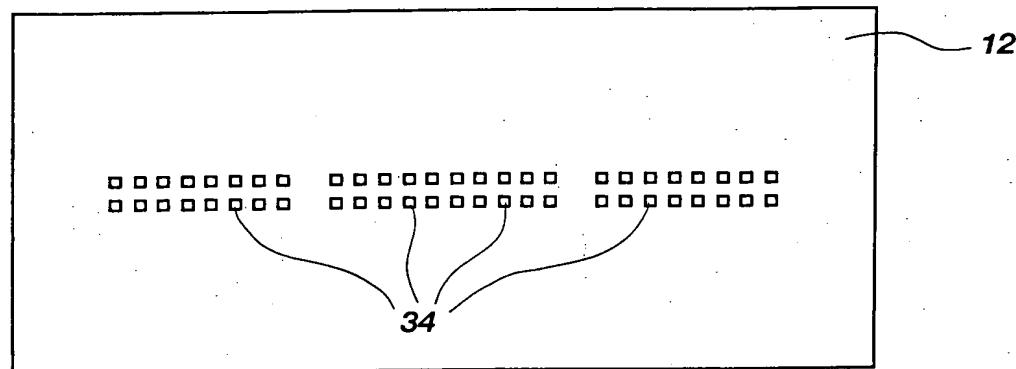


FIG. 9

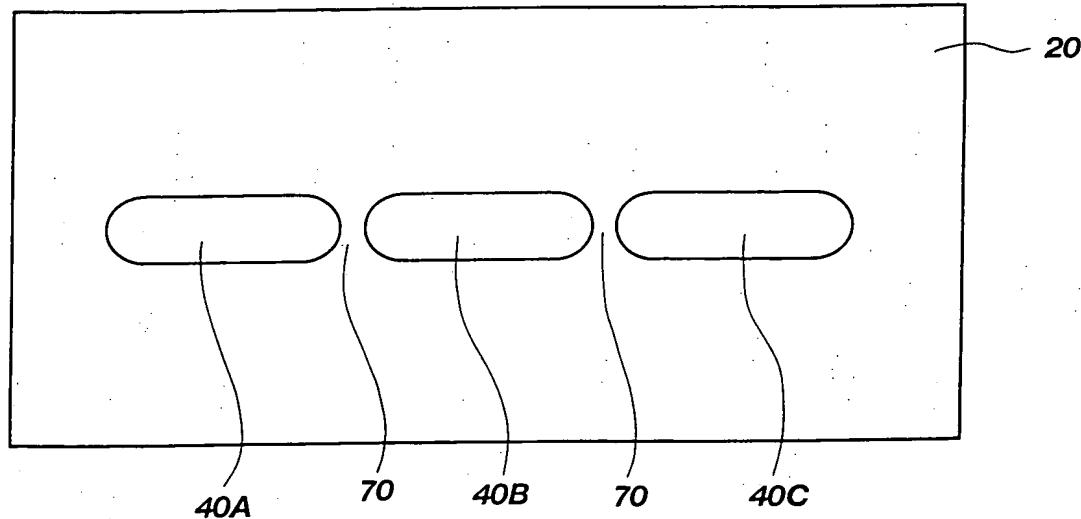


FIG. 9A

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